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NEWS RELEASE

Enhanced Production Capacity of MicroThin™ for Package Substrates

- Enhancing production capacity of Ageo Copper Foil Plant to 2.5 million m² per month -

Mitsui Mining & Smelting Co., Ltd. (President: Takeshi Nou; “Mitsui Kinzoku” hereinafter) is pleased to announce today that it has enhanced production capacity of extremely-thin electrodeposited copper foil with carrier for package substrate at Ageo plant (Ageo City, Saitama, Japan) by 0.5 million m² and achieved production volume of 2.5 million m² per month.

MicroThin™, extremely-thin electrodeposited copper foil with carrier is a product of Mitsui Kinzoku that has a copper foil of thickness 1.5 μm to 5 μm suitable for forming fine circuits and multiple types of fine-roughening treatment, and is mainly used for package substrate and motherboard for smartphones.

Demand for MicroThin™ for package substrate is expected to grow because electronic components used in smartphones have increased in association with the advance of 5G and other functions. Aside from in smartphones, use of the product has also expanded to memory substrates for data centers and automotive applications.

For this reason, the Ageo plant, our mother plant, has enhanced its production capacity from 2.0 million m² to 2.5 million m² per month without making a large equipment investment by improving technical coefficient, such as operating rate and yield, and is moving forward with its digital transformation to collect and analyze manufacturing data while improving labor productivity by increasing the engagement of its employees through work satisfaction reforms.

This increase, combined with the 2.4 million m² per month production capacity of the plant in Malaysia (Mitsui Copper Foil (Malaysia) SDN.BHD.), means that Mitsui Kinzoku’s total production capacity of MicroThin™ has increased from 4.4 million m² to 4.9 million m² per month, ensuring that it is completely prepared to cater to the increased demand. Moreover, Mitsui Kinzoku will consider implementing the Ageo plant’s initiatives in the plant in Malaysia in the future.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing our its vision for

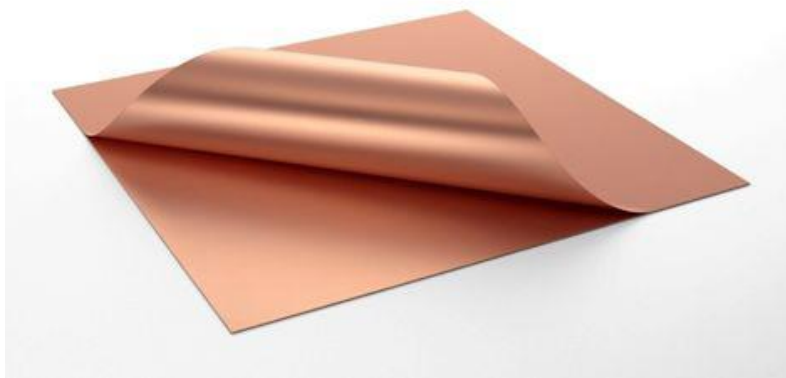
2030, “Building new businesses — and the future— with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

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Picture of MicroThin™



Top: Copper carrier foil (thickness: 18 μ m or 12 μ m)

Bottom: Extremely-thin copper foil (thickness: 1.5 μ m to 5 μ m)